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- 8-Bit Resolution
- Easy Microprocessor Interface or Stand-Alone Operation
- Operates Ratiometrically or With 5-V Reference
- 4- or 8-Channel Multiplexer Options With Address Logic
- Input Range 0 to 5 V With Single 5-V Supply
- Remote Operation With Serial Data Link

 Inputs and Outputs Are Compatible With TTL and MOS

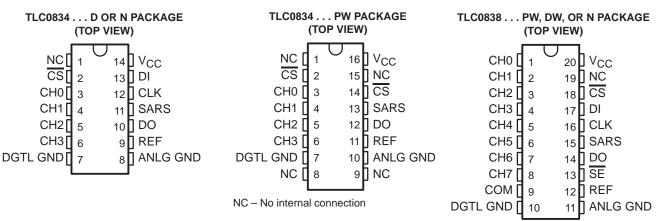
- Conversion Time of 32 μs at f_{clock} = 250 kHz
- Functionally Equivalent to the ADC0834 and ADC0838 Without the Internal Zener Regulator Network
- Total Unadjusted Error . . . ±1 LSB

description

These devices are 8-bit successive- approximation analog-to-digital converters, each with an input-configurable multichannel multiplexer and serial input/output. The serial input/ output is configured to interface with standard shift registers or microprocessors. Detailed information on interfacing with most popular microprocessors is readily available from the factory.

The TLC0834 (4-channel) and TLC0838 (8-channel) multiplexer is software-configured for single-ended or differential inputs as well as pseudodifferential input assignments. The differential analog voltage input allows for common-mode rejection or offset of the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding of any smaller analog voltage span to the full 8 bits of resolution.

The TLC0834C and TLC0838C are characterized for operation from 0° C to 70° C. The TLC0834I and TLC0838I are characterized for operation from -40° C to 85° C. The TLC0834Q is characterized for operation from -40° C to 125° C.



AVAILABLE OPTIONS

			PACKAGE	
TA	T _A SMALL OUTLINE (D) SMALL OUTLINE (DW)		PLASTIC DIP (N)	TSSOP (PW)
0°C to 70°C	TLC0834CD	TLC0838CDW	TLC0834CN TLC0838CN	TLC0834CPW TLC0838CPW
-40°C to 85°C	TLC0834ID	TLC0838IDW	TLC0834IN TLC0838IN	TLC0834IPW TLC0838IPW
-40°C to 125°C	_	_	TLC0834QN —	_



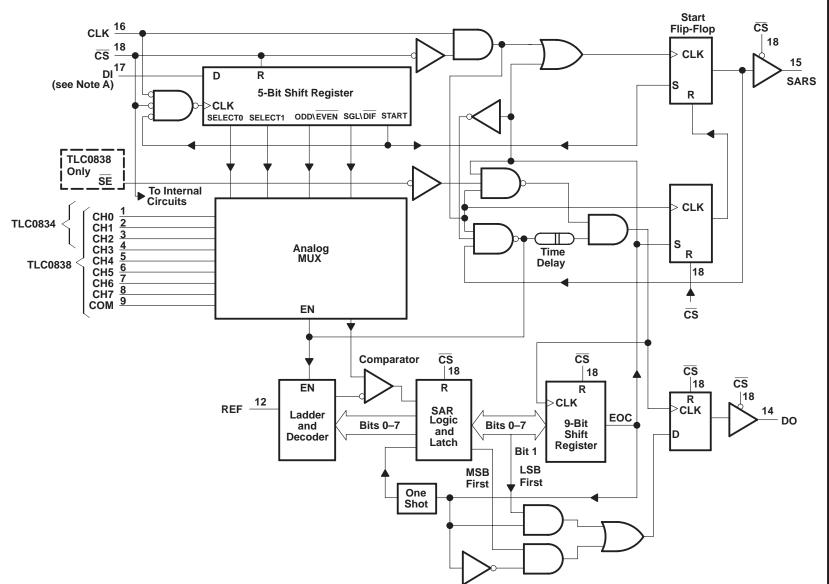
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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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functional block diagram



NOTES A: For the TLC0834, DI is input directly to the D input of SELECT1; SELECT0 is forced to a high. B: Terminal numbers shown are for the DW or N package.

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TLC0834C, TLC0834I, TLC0838C, TLC0838I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

functional description

The TLC0834 and TLC0838 use a sample-data-comparator structure that converts differential analog inputs by a successive-approximation routine. Operation of both devices is similar with the exception of \overline{SE} , an analog common input, and multiplexer addressing. The input voltage to be converted is applied to a channel terminal and is compared to ground (single ended), to an adjacent input (differential), or to a common terminal (pseudo differential) that can be an arbitrary voltage. The input terminals are assigned a positive (+) or negative (-) polarity. When the signal input applied to the assigned positive terminal is less than the signal on the negative terminal, the converter output is all zeros.

Channel selection and input configuration are under software control using a serial-data link from the controlling processor. A serial-communication format allows more functions to be included in a converter package with no increase in size. In addition, it eliminates the transmission of low-level analog signals by locating the converter at the analog sensor and communicating serially with the controlling processor. This process returns noise-free digital data to the processor.

A particular input configuration is assigned during the multiplexer-addressing sequence. The multiplexer address shifts into the converter through the data input (DI) line. The multiplexer address selects the analog inputs to be enabled and determines whether the input is single ended or differential. When the input is differential, the polarity of the channel input is assigned. Differential inputs are assigned to adjacent channel pairs. For example, channel 0 and channel 1 may be selected as a differential pair. These channels cannot act differentially with any other channel. In addition to selecting the differential mode, the polarity may also be selected. Either channel of the channel pair may be designated as the negative or positive input.

The common input on the TLC0838 can be used for a pseudodifferential input. In this mode, the voltage on the common input is considered to be the negative differential input for all channel inputs. This voltage can be any reference potential common to all channel inputs. Each channel input can then be selected as the positive differential input. This feature is useful when all analog circuits are biased to a potential other than ground.

A conversion is initiated by setting \overline{CS} low, which enables all logic circuits. \overline{CS} must be held low for the complete conversion process. A clock input is then received from the processor. On each low-to-high transition of the clock input, the data on DI is clocked into the multiplexer-address shift register. The first logic high on the input is the start bit. A 3- to 4-bit assignment word follows the start bit. On each successive low-to-high transition of the clock input, the start bit and assignment word are shifted through the shift register. When the start bit is shifted into the start location of the multiplexer register, the input channel is selected and conversion starts. The SAR status output (SARS) goes high to indicate that a conversion is in progress, and DI to the multiplexer shift register is disabled for the duration of the conversion.

An interval of one clock period is automatically inserted to allow the selected multiplexed channel to settle. DO comes out of the high-impedance state and provides a leading low for one clock period of multiplexer settling time. The SAR comparator compares successive outputs from the resistive ladder with the incoming analog signal. The comparator output indicates whether the analog input is greater than or less than the resistive-ladder output. As the conversion proceeds, conversion data is simultaneously output from DO, with the most significant bit (MSB) first. After eight clock periods, the conversion is complete and SARS goes low.

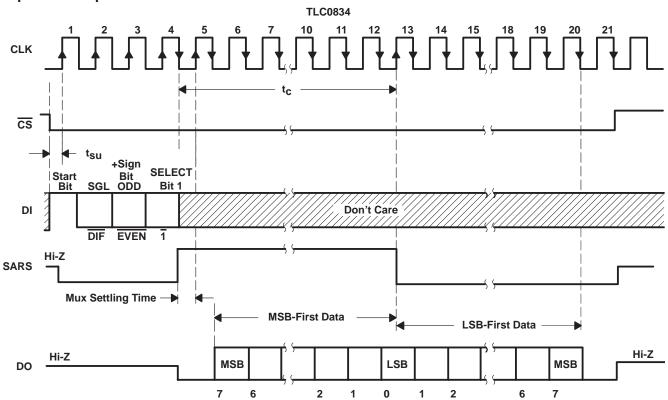
The TLC0834 outputs the least-significant-bit (LSB) first data after the MSB-first data stream. When \overline{SE} is held high on the TLC0838, the value of the LSB remains on the data line. When \overline{SE} is forced low, the data is then clocked out as LSB-first data. (To output LSB first, \overline{SE} must first go low, then the data stored in the 9-bit shift register outputs LSB first.) When \overline{CS} goes high, all internal registers are cleared. At this time, the output circuits go to the high-impedance state. If another conversion is desired, \overline{CS} must make a high-to-low transition followed by address information.

DI and DO can be tied together and controlled by a bidirectional processor I/O bit received on a single wire. This is possible because DI is only examined during the multiplexer-addressing interval and DO is still in the high-impedance state.



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sequence of operation



TLC0834 MUX-ADDRESS CONTROL LOGIC TABLE

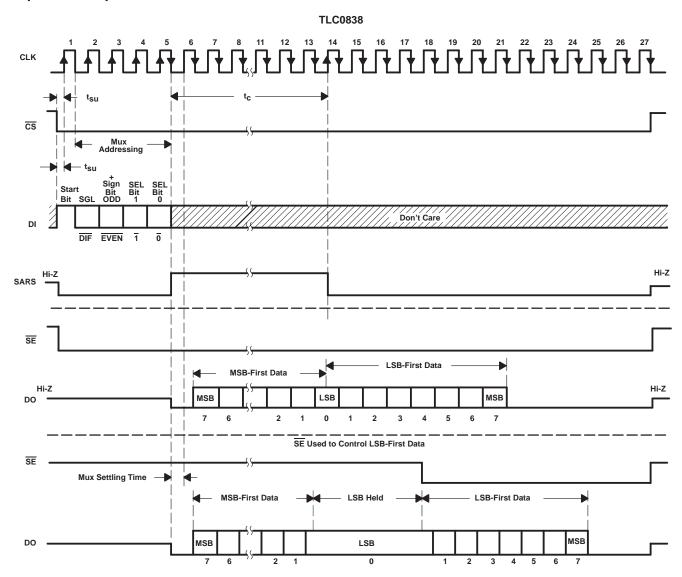
	MUX ADDRE	SS	СНА	NNEL	NUMB	ER
SGL/DIF	ODD/EVEN	SELECT BIT 1	CH0	CH1	CH2	CH3
L	L	L	+	-		
L	L	Н			+	-
L	Н	L	-	+		
L	Н	Н			-	+
Н	L	L	+			
Н	L	Н			+	
Н	Н	L		+		
Н	Н	Н				+
L high lavel		, torminal palarity	fortha	alaata	الاردى مى مى الم	-

H = high level, L = low level, - or + = terminal polarity for the selected input channel



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sequence of operation





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	TLC0838 MUX-ADDRESS CONTROL LOGIC TABLE MUX ADDRESS SELECTED CHANNEL NUMBER													
	MUX ADDRESS				SE	LECTE	D CHA	NNEL	NUMB	ER				
SGL/DIF	ODD/EVEN	SEL	ЕСТ		0		1		2		3	сом		
SGL/DIF	ODD/EVEN	1	0	CH0	CH1	CH2	CH3	CH4	CH5	CH6	CH7			
L	L	L	L	+	-									
L	L	L	н			+	-							
L	L	н	L					+	-					
L	L	н	н							+	-			
L	Н	L	L	-	+									
L	н	L	н			-	+							
L	н	н	L					-	+					
L	Н	н	н							-	+			
Н	L	L	L	+								-		
Н	L	L	н			+						-		
н	L	н	L					+				-		
н	L	н	н							+		-		
Н	Н	L	L		+							-		
н	н	L	н				+					-		
н	н	н	L						+			-		
н	н	н	н		-	_		-			+	-		

TI CARADA MULY ADDDESS CONTROL LOGIC TADLE

H = high level, L = low level, - or + = polarity of external input

absolute maximum ratings over recommended operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1) Input voltage range: Logic Analog	$\dots \dots \dots \dots -0.3$ V to V _{CC} + 0.3 V
Input current, I ₁	
Total input current	
Operating free-air temperature range, T_A : C suffix	
Storage temperature range, T _{stg} Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N pacl	kage 260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to the network ground terminal.



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recommended operating conditions

		MIN	NOM	MAX	UNIT	
Supply voltage, V _{CC}		4.5	5	5.5	V	
High-level input voltage, VIH		2			V	
Low-level input voltage, VIL				0.8	V	
Clock frequency, f _(clock)		10		600	kHz	
Clock duty cycle (see Note 2)		40%	40% 60%			
Pulse duration, CS high, t _W		220			ns	
Setup time, CS low, SE low, or data valid befo	re CLK↑, t _{SU} (see Figures 1 and 2)	350			ns	
Hold time, data valid after CLK^{\uparrow} , t _h (see Figu	re 1)	90			ns	
	C suffix	0		70		
Operating free-air temperature, T _A	l suffix	-40		85	°C	

NOTE 2: The clock-duty-cycle range ensures proper operation at all clock frequencies. When a clock frequency is used outside the recommended duty-cycle range, the minimum pulse duration (high or low) is 1 µs.

electrical characteristics over recommended range of operating free-air temperature, $V_{CC} = 5 V$, $f_{(clock)} = 250 \text{ kHz}$ (unless otherwise noted)

digital section

				(C SUFFIX		I	SUFFIX		
	PARAMETER	TEST CO	NDITIONS [†]	MIN	TYP‡	MAX	MIN	typ‡	MAX	UNIT
Val	High-level output voltage	V _{CC} = 4.75 V,	$I_{OH} = -360 \mu A$	2.8			2.4			V
Vон	nigh-level output voltage	V _{CC} = 4.75 V,	I _{OH} = -10 μA	4.6			4.5			v
VOL	Low-level output voltage	V _{CC} = 5.25 V,	I _{OL} = 1.6 mA			0.34			0.4	V
lιн	High-level input current	VIH = 5 V,	VIH = 5 V		0.005	1		0.005	1	μA
ΙL	Low-level input current	$V_{IL} = 0,$	$V_{IL} = 0$		-0.005	-1		-0.005	-1	μA
ЮН	High-level output (source) current	V _{OH} = 0,	$T_A = 25^{\circ}C$	-6.5	-24		-6.5	-24		mA
IOL	Low-level output (sink) current	$V_{OL} = V_{CC},$	$T_A = 25^{\circ}C$	8	26		8	26		mA
	High-impedance-state output	V _O = 5 V,	$T_A = 25^{\circ}C$		0.01	3		0.01	3	A
loz	current (DO or SARS)	$V_{O} = 0,$	$T_A = 25^{\circ}C$		-0.01	-3		-0.01	-3	μA
Ci	Input capacitance							5		pF
Co	Output capacitance							5		pF

[†] All parameters are measured under open-loop conditions with zero common-mode input voltage (unless otherwise specified).
 [‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.



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electrical characteristics over recommended range of operating free-air temperature, $V_{CC} = 5 V$, $f_{(clock)} = 250 \text{ kHz}$ (unless otherwise noted) (continued)

analog and converter section

	PARAMETER		TEST CONDITIONS [†]	MIN	TYP‡	MAX	UNIT
VIC	Common-mode input voltage		See Note 3	-0.05 to V _{CC} +0.05			V
		On channel	V _I = 5 V			1	
ter an a	Standby input surrent (ass Note 4)	Off channel	$V_{I} = 0$			-1	
II(stdby)	Standby input current (see Note 4)	On channel	VI = 0			-1	μA
		Off channel VI = 5 V				1	
^r i(REF)	Input resistance to REF			1.3	2.4	5.9	kΩ

[†] All parameters are measured under open-loop conditions with zero common-mode input voltage.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

NOTES: 3. When channel IN- is more positive than channel IN+, the digital output code is 0000 0000. Connected to each analog input are two on-chip diodes that conduct forward current for analog input voltages one diode drop above V_{CC}. Care must be taken during testing at low V_{CC} levels (4.5 V) because high-level analog input voltage (5 V) can, especially at high temperatures, cause the input diode to conduct and cause errors for analog inputs that are near full scale. As long as the analog voltage does not exceed the supply voltage by more than 50 mV, the output code is correct. To achieve an absolute 0- to 5-V input range requires a minimum V_{CC} of 4.950 V for all variations of temperature and load.

4. Standby input currents go in or out of the on or off channels when the A/D converter is not performing conversion and the clock is in a high or low steady-state condition.

total device

	PARAMETER	MIN	typ‡	MAX	UNIT
ICC	Supply current		0.6	1.25	mA

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

operating characteristics, V_{CC} = 5 V, $f_{(clock)}$ = 250 kHz, t_r = t_f = 20 ns, T_A = 25°C (unless otherwise noted)

	PARAMETER		TEST C	CONDITIONS§	MIN	TYP	MAX	UNIT
	Supply-voltage variation error		V _{CC} = 4.75 \	/ to 5.25 V		±1/16	±1/4	LSB
	Total unadjusted error (see Note 5)		V _{ref} = 5 V,	$T_A = MIN$ to MAX			±1	LSB
	Common-mode error	Differential m	ode		±1/16	±1/4	LSB	
÷ .	Propagation delay time, output	MSB-first data	C _I = 100 pF			1500	20	
^t pd	data after CLK \downarrow (see Note 6 and Figure 2)	LSB-first data					600	ns
+			C _L = 10 pF,	RL = 10 kΩ			250	ns
^t dis	Output disable time, DO or SARS after CS1	(see Figure 3)	C _L = 100 pF,	$R_L = 2 k\Omega$			500	115
t _C	Conversion time (multiplexer-addressing time					8	clock periods	

§ All parameters are measured under open-loop conditions with zero common-mode input voltage. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Total unadjusted error includes offset, full-scale, linearity, and multiplexer errors.

6. The MSB-first data is output directly from the comparator and, therefore, requires additional delay to allow for comparator response time.



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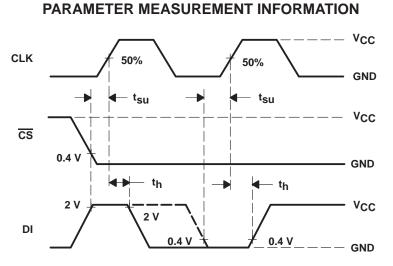


Figure 1. Data-Input Timing

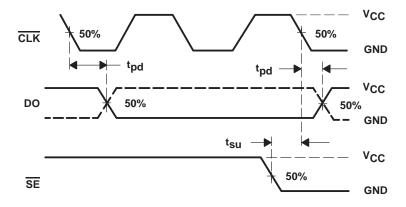
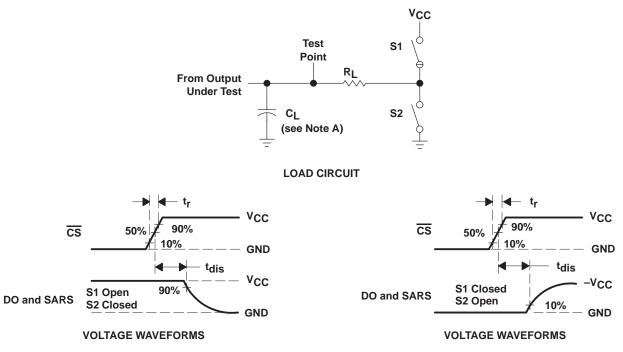


Figure 2. Data-Output Timing



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PARAMETER MEASUREMENT INFORMATION

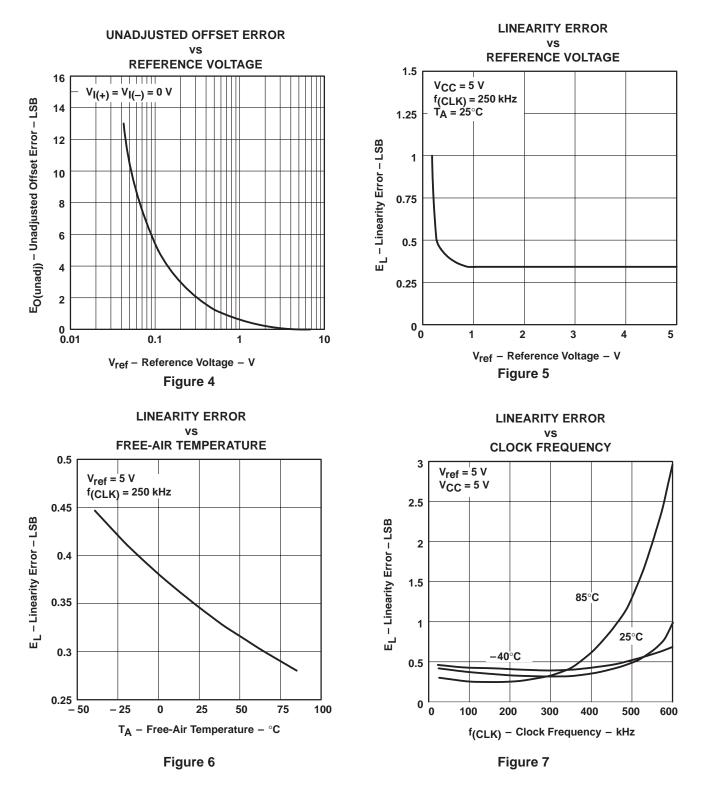
NOTE A: CI includes probe and jig capacitance.





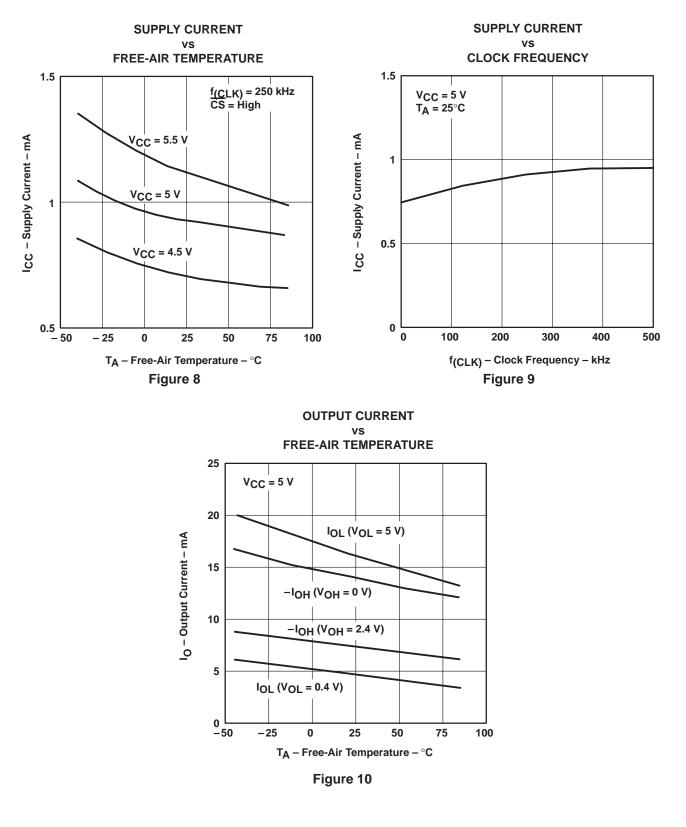
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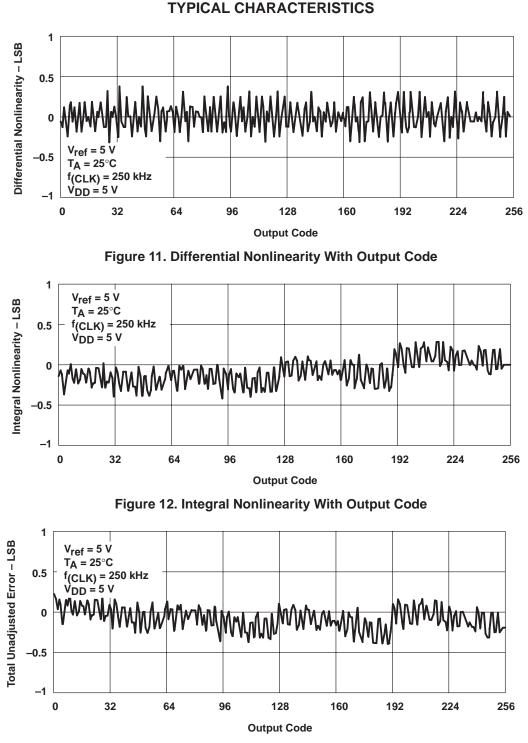
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TYPICAL CHARACTERISTICS



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17-Mar-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLC0834CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC0834C	Samples
TLC0834CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC0834C	Samples
TLC0834CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0834C	Samples
TLC0834CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0834C	Samples
TLC0834CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC0834CN	Samples
TLC0834CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC0834CN	Samples
TLC0834ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC08341	Samples
TLC0834IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC08341	Samples
TLC0834IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC08341	Samples
TLC0834IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC0834IN	Samples
TLC0834INE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC0834IN	Samples
TLC0838CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838C	Samples
TLC0838CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838C	Samples
TLC0838CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838C	Samples
TLC0838CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838C	Samples
TLC0838CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC0838CN	Samples
TLC0838CPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC0838C	Samples



PACKAGE OPTION ADDENDUM

17-Mar-2017

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TLC0838CPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(4/3) TLC0838C	Samples
TLC0838CPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC0838C	Samples
TLC0838CPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC0838C	Samples
TLC0838IDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838I	Samples
TLC0838IDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838I	Samples
TLC0838IDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838I	Samples
TLC0838IDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC0838I	Samples
TLC0838IN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TLC0838IN	Samples
TLC0838INE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TLC0838IN	Samples
TLC0838IPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC0838I	Samples
TLC0838IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC0838I	Samples
TLC0838IPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC0838I	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.



PACKAGE OPTION ADDENDUM

17-Mar-2017

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC0834CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC0834IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC0838CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TLC0838IDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC0838IDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC0838IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC0834CDR	SOIC	D	14	2500	367.0	367.0	38.0
TLC0834IDR	SOIC	D	14	2500	367.0	367.0	38.0
TLC0838CPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TLC0838IDWR	SOIC	DW	20	2000	367.0	367.0	45.0
TLC0838IDWR	SOIC	DW	20	2000	367.0	367.0	45.0
TLC0838IPWR	TSSOP	PW	20	2000	367.0	367.0	38.0

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